PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3737097

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAIZO TOSAKA	02/05/2016
HIROSHI MIYAZAKI	02/03/2016
SADANORI IWAI	02/03/2016
SHIGEKI TAKAYAMA	02/03/2016
KEI KOYANAGI	02/03/2016
KENJI TASAKI	02/03/2016

RECEIVING PARTY DATA

Name:	KABUSHIKI KAISHA TOSHIBA
Street Address:	1-1, SHIBAURA 1-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-8001

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15042449

CORRESPONDENCE DATA

Fax Number: (703)413-2220

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (703) 413-3000 knewett@oblon.com Email: **Correspondent Name:** OBLON, ET AL. Address Line 1: 1940 DUKE STREET

Address Line 4: ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	466922US20
NAME OF SUBMITTER:	KRISTIN NEWETT
SIGNATURE:	/Kristin Newett/
DATE SIGNED:	02/12/2016
	This document serves as an Oath/Declaration (37 CFR 1.63).

PATENT REEL: 037724 FRAME: 0236

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Total Attachments: 6 source=466922US20ASN#page1.tif source=466922US20ASN#page2.tif source=466922US20ASN#page3.tif source=466922US20ASN#page4.tif source=466922US20ASN#page5.tif source=466922US20ASN#page6.tif

Title of CONNECTION STRUCTURE OF HIGH-TEMPERATURE SUPERCONDUCTING WIRE PIECE, HIGH-TEMPERATURE SUPERCONDUCTING WIRE USING CONNECTION STRUCTURE, AND HIGH-TEMPERATURE SUPERCONDUCTING COIL USING CONNECTION STRUCTURE As the below named inventor, I hereby declare that:	
This declaration The attached application, or	
The above-identified application was made or authorized to be made by me.	
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.	
WHEREAS, KABUSHIKI KAISHA TOSHIBA (hereinafter referred to as "ASSIGNEE") having places of business at: 1-1, Shibaura 1-Chome, Minato-Ku, Tokyo 105-8001 Japan, is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;	
NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I, by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries (including the right to claim priority under the terms of the International Convention and other relevant International Treaties and Arrangements from the aforesaid application) and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.	
I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.	
Further, I agree that I will communicate to said ASSIGNEE or its (his) representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.	
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.	
LEGAL NAME OF INVENTOR	
Inventor: Taizo TOSAKA Date: Feb. 5, 2016	
Signature: T. Tosaka	

OBLON, McCLELLAND, MAIER & NEUSTADT, L.L.P.
ATTORNEYS AT LAW
1940 DUKE STREET
ALEXANDRIA, VIRGINIA 22314

Invention CONNECTION STRUCTURE OF HIGH-TEMPERATURE SUPERCONDUCTING WIRE PIECE, HIGH-TEMPERATURE SUPERCONDUCTING WIRE USING CONNECTION STRUCTURE, AND HIGH-TEMPERATURE SUPERCONDUCTING COIL USING CONNECTION STRUCTURE
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LEGAL NAME OF INVENTOR
Inventor: Hiroshi MIYAZAKI Date: Feb. 3, 2016
Signature: H. Miyazaki

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LEGAL NAME OF INVENTOR	
Inventor: Sadanori IWAI Date: Feb 3 20/6	
Signature: <u>Andonovi Lvol</u>	

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LEGAL NAME OF INVENTOR	
Inventor: Shigeki TAKAYAMA Date: Feb. 3, 2616	
Signature: S. Takayana	

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LEGAL NAME OF INVENTOR	
Inventor: Kei KOYANAGI Date: 7, 2016	
Signature: K. Koyamogi	

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Invention CONNECTION STRUCTURE OF HIGH-TEMPERATURE SUPERCONDUCTING WIRE PIECE, HIGH-TEMPERATURE SUPERCONDUCTING WIRE USING CONNECTION STRUCTURE, AND HIGH-TEMPERATURE SUPERCONDUCTING COIL USING CONNECTION STRUCTURE	
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LEGAL NAME OF INVENTOR	
Inventor: Kenji TASAKI Date: February 3, 2016	
Signature: Kenji Tasaki	

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> PATENT REEL: 037724 FRAME: 0243

RECORDED: 02/12/2016